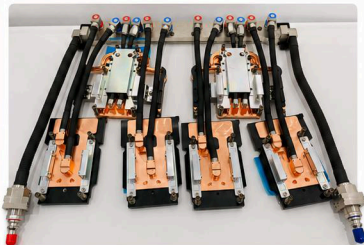


GB300-Class Copper Liquid Cold Plate

Thermal Performance & Pressure Drop Test Summary

OVERVIEW

- Batch-validated solution for high-power AI server GPU / CPU liquid cooling
- Model: TC-BZP-GB300-01A
- Test condition: Steady-state
- Test fluid: Pure water
- Test date: 2026/03/20
- Suitable for corrosion / erosion degradation studies, coolant compatibility testing, and liquid cooling evaluation



GPU Cold Plate Test Data

Parameter	Value
Flow rate	1.7 L/min
Thermal interface material	TC-5888 thermal paste
Heat load	1066.94 W
Inlet temperature	19.9 C
Outlet temperature	27.3 C
T1 measured temperature	34.1 C
T2 measured temperature	33.8 C
T1 temperature rise vs inlet	14.2 C
T2 temperature rise vs inlet	13.9 C
Pressure drop	12.06 kPa
Thermal resistance (T1)	0.0133 C/W
Thermal resistance (T2)	0.0130 C/W

CPU Cold Plate Test Data

Parameter	Value
Flow rate	0.7 L/min
Thermal interface material	TC-5888 thermal paste
Heat load	485.46 W
Inlet temperature	23.6 C
Outlet temperature	31.5 C
T1 measured temperature	34.3 C
T1 temperature rise vs inlet	10.7 C
Pressure drop	10.39 kPa
Thermal resistance	0.0220 C/W